

2SC3187

Silicon NPN triple diffusion planar type

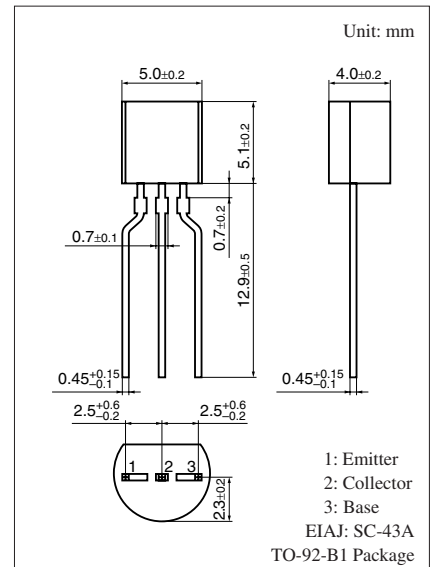
For small TV video output

■ Features

- High collector-emitter voltage (Base open) V_{CEO}
- Small collector output capacitance (Common base, input open circuited) C_{ob}

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

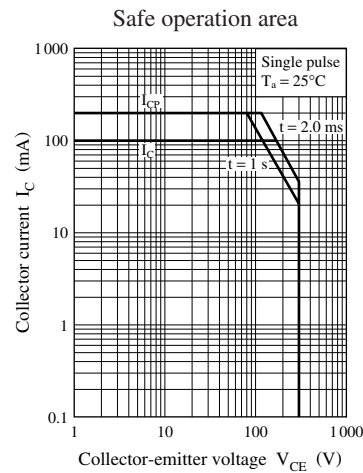
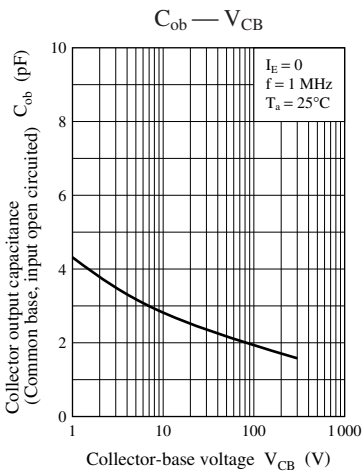
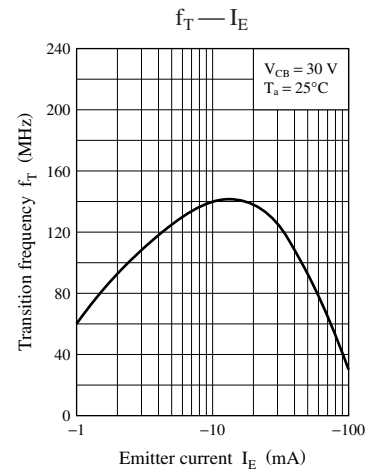
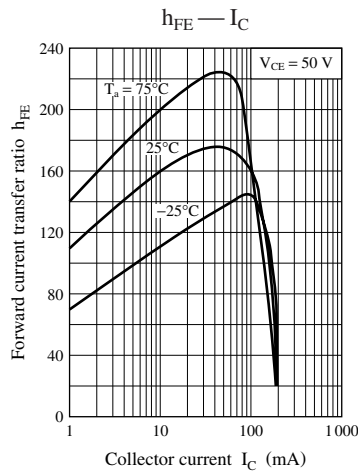
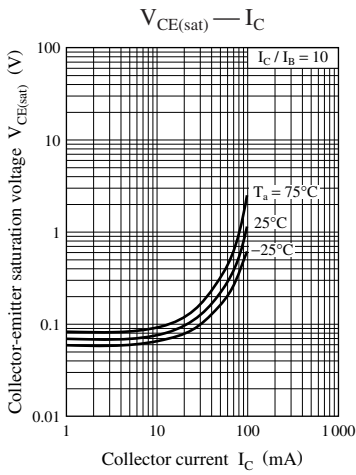
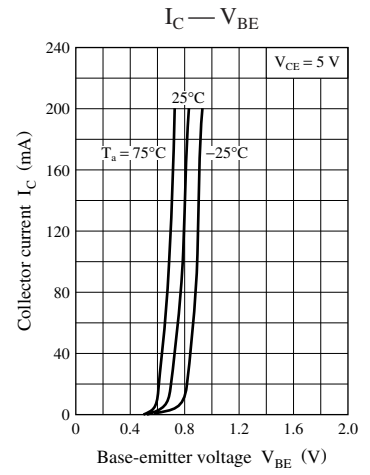
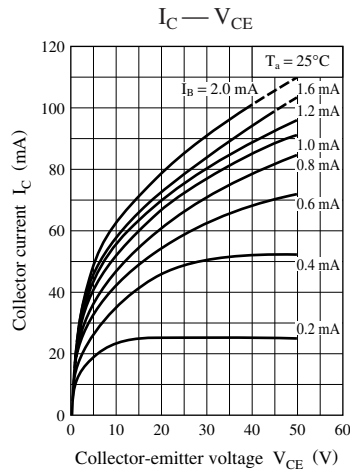
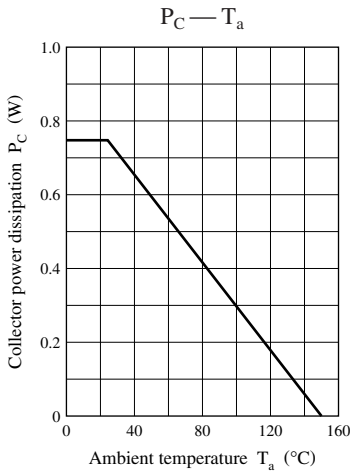
Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	300	V
Collector-emitter voltage (Base open)	V_{CEO}	300	V
Emitter-base voltage (Collector open)	V_{EBO}	7	V
Collector current	I_C	100	mA
Peak collector current	I_{CP}	200	mA
Collector power dissipation	P_C	750	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$



■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = 10 \mu\text{A}$, $I_E = 0$	300			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = 100 \mu\text{A}$, $I_B = 0$	300			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 10 \mu\text{A}$, $I_C = 0$	7			V
Base-emitter voltage	V_{BE}	$V_{CE} = 10 \text{V}$, $I_C = 30 \text{mA}$			1.2	V
Forward current transfer ratio	h_{FE}	$V_{CE} = 50 \text{V}$, $I_C = 5 \text{mA}$	50		250	—
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = 30 \text{mA}$, $I_B = 3 \text{mA}$			1.5	V
Transition frequency	f_T	$V_{CB} = 30 \text{V}$, $I_E = -20 \text{mA}$, $f = 200 \text{MHz}$	70	140		MHz
Collector output capacitance (Common base, input open circuited)	C_{ob}	$V_{CB} = 30 \text{V}$, $I_E = 0$, $f = 1 \text{MHz}$		1.9		pF

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.



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